

Features

- Temperature protection provided by directly detecting the junction temperature of the IGBTs
- Low power loss and soft switching
- High performance and high reliability IGBT with overheating protection
- Higher reliability because of a big decrease in number of parts in built-in control circuit



Maximum ratings and characteristics

- Absolute maximum ratings(at Tc=25°C unless otherwise specified)

Item	Symbol	Rating		Unit		
		Min.	Max.			
Bus voltage	DC	VDC	0	450	V	
	Surge	VDC(surge)	0	500	V	
	Short operating	VSC	200	400	V	
Collector-Emitter voltage *1	VCEs		0	600	V	
Inverter	Collector current	DC	IC	-	150	A
		1ms	ICP	-	300	A
		Duty=68.2% *2	-IC	-	150	A
	Collector power dissipation	One transistor *3	PC	-	431	W
Supply voltage of Pre-Driver *4	VCC		-0.5	20	V	
Input signal voltage *5	Vin		-0.5	Vcc+0.5	V	
Input signal current	Iin		-	3	mA	
Alarm signal voltage *6	VALM		-0.5	Vcc	V	
Alarm signal current *7	IALM		-	20	mA	
Junction temperature	Tj		-	150	°C	
Operating case temperature	Topr		-20	100	°C	
Storage temperature	Tstg		-40	125	°C	
Solder temperature *8	Tsol		-	260	°C	
Isolating voltage (Terminal to base, 50/60Hz sine wave 1min.)	Viso		-	AC2500	V	
Screw torque	Mounting (M5)		-	3.5	Nm	

Note

*1 : Vces shall be applied to the input voltage between terminal P and U or ,u or W, N and U or V or W

*2 : $125^{\circ}\text{C}/\text{FWD } R_{\text{th}}(\text{j-c})/(\text{Ic} \times \text{VF MAX})=125/0.47/(150 \times 2.6) \times 100=68.2\%$

*3 : $P_c=125^{\circ}\text{C}/\text{IGBT } R_{\text{th}}(\text{j-c})=125/0.29=431\text{W}$ [Inverter]

*4 : VCC shall be applied to the input voltage between terminal No.4 and 1, 8 and 5, 12 and 9, 14 and 13

*5 : Vin shall be applied to the input voltage between terminal No.3 and 1, 7 and 5, 11 and 9, 16,17,18 and 13.

*6 : VALM shall be applied to the voltage between terminal No.2 and 1, No6 and 5, No10 and 9, No.19 and 13.

*7 : IALM shall be applied to the input current to terminal No.2,6,10 and 19.

*8 : Immersion time 10±1sec.

● **Electrical characteristics** (at $T_c=T_j=25^\circ\text{C}$, $V_{cc}=15\text{V}$ unless otherwise specified.)

Main circuit

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	
Inverter	Collector current at off signal input	I_{CES}	$V_{CE}=600\text{V}$ V_{in} terminal open.	-	-	1.0	mA	
	Collector-Emitter saturation voltage	$V_{CE(sat)}$	$I_c=150\text{A}$	Terminal	-	-	2.3	V
				Chip	-	1.8	-	
	Forward voltage of FWD	V_F	$-I_c=150\text{A}$	Terminal	-	-	2.6	V
Chip				-	1.6	-		
Turn-on time		t_{on}	$V_{DC}=300\text{V}, T_j=125^\circ\text{C}$	1.2	-	-	μs	
Turn-off time		t_{off}	$I_C=150\text{A}$ Fig.1, Fig.6	-	-	3.6		
Reverse recovery time		t_{rr}	$V_{DC}=300\text{V}, I_C=150\text{A}$ Fig.1, Fig.6	-	-	0.3		
Maximum Avalanche Energy (A non-repetition)		P_{AV}	Internal wiring inductance=50nH Main circuit wiring inductance=54nH	170	-	-	mJ	

● **Control circuit**

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Supply current of P-line side pre-driver(one unit)	I_{ccp}	Switching Frequency : 0 to 15kHz $T_c=-20$ to 125°C Fig.7	-	-	18	mA
Supply current of N-line side pre-driver	I_{ccn}		-	-	65	mA
Input signal threshold voltage (on/off)	$V_{in(th)}$	ON	1.00	1.35	1.70	V
		OFF	1.25	1.60	1.95	V
Input zener voltage	V_Z	$R_{in}=20\text{k ohm}$	-	8.0	-	V
Alarm signal hold time	t_{ALM}	$T_c=-20^\circ\text{C}$ Fig.2	1.1	-	-	ms
		$T_c=25^\circ\text{C}$ Fig.2	-	2.0	-	ms
		$T_c=125^\circ\text{C}$ Fig.2	-	-	4.0	ms
Current limit resistor	R_{ALM}	Alarm terminal	1425	1500	1575	ohm

● **Protection Section** ($V_{cc}=15\text{V}$)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Over Current Protection Level of Inverter circuit	I_{oc}	$T_j=125^\circ\text{C}$	225	-	-	A
Over Current Protection Delay time	t_{DOC}	$T_j=125^\circ\text{C}$	-	5	-	μs
SC Protection Delay time	t_{SC}	$T_j=125^\circ\text{C}$ Fig.4	-	-	8	μs
IGBT Chip Over Heating	T_{jOH}	Surface of IGBT chips	150	-	-	$^\circ\text{C}$
Over Heating Protection Hysteresis	T_{jH}		-	20	-	$^\circ\text{C}$
Under Voltage Protection Level	V_{UV}		11.0	-	12.5	V
Under Voltage Protection Hysteresis	V_H		0.2	0.5	-	V

● **Thermal characteristics**($T_c=25^\circ\text{C}$)

Item			Symbol	Min.	Typ.	Max.	Unit
Junction to Case thermal resistance *10	Inverter	IGBT	$R_{th(j-c)}$	-	-	0.29	$^\circ\text{C/W}$
		FWD	$R_{th(j-c)}$	-	-	0.47	$^\circ\text{C/W}$
Case to fin thermal resistance with compound			$R_{th(c-f)}$	-	0.05	-	$^\circ\text{C/W}$

*10 : (For 1 device, Case is under the device)

● **Noise Immunity** ($V_{DC}=300\text{V}$, $V_{cc}=15\text{V}$, Test Circuit Fig.5)

Item	Condition	Min.	Typ.	Max.	Unit
Common mode rectangular noise	Pulse width $1\mu\text{s}$, polarity \pm , 10minuets Judge : no over-current, no miss operating	± 2.0	-	-	kV
Common mode lightning surge	Rise time $1.2\mu\text{s}$, Fall time $50\mu\text{s}$ Interval 20s, 10 times Judge : no over-current, no miss operating	± 5.0	-	-	kV

● **Recommendable value**

Item	Symbol	Min.	Typ.	Max.	Unit
DC Bus Voltage	V_{DC}	-	-	400	V
Operating Supply Voltage of Pre-Driver	V_{cc}	13.5	15.0	16.5	V
Screw torque (M5)	-	2.5	-	3.0	Nm

● **Weight**

Item	Symbol	Min.	Typ.	Max.	Unit
Weight	W_t	-	270	-	g

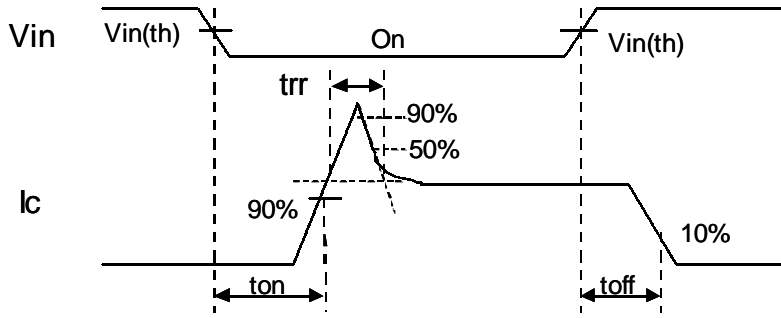
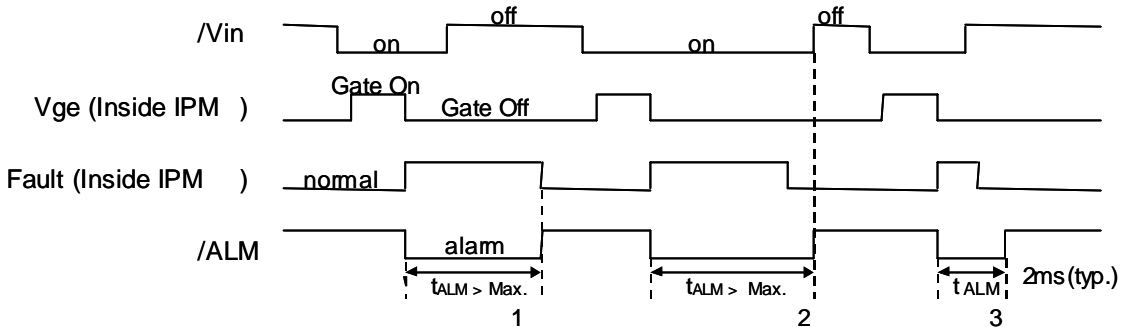


Figure 1. Switching Time Waveform Definitions



Fault : Over-current, Over-heat or Under-voltage

Figure 2. Input/Output Timing Diagram

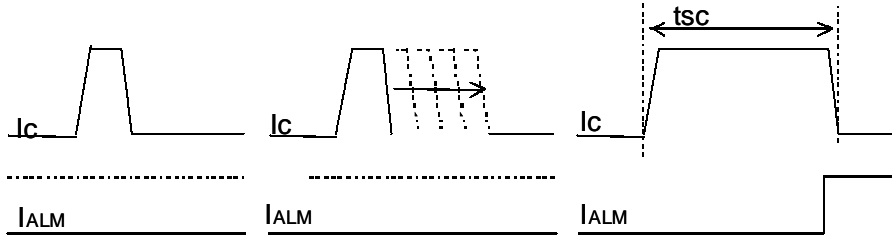


Figure.4 Definition of tsc

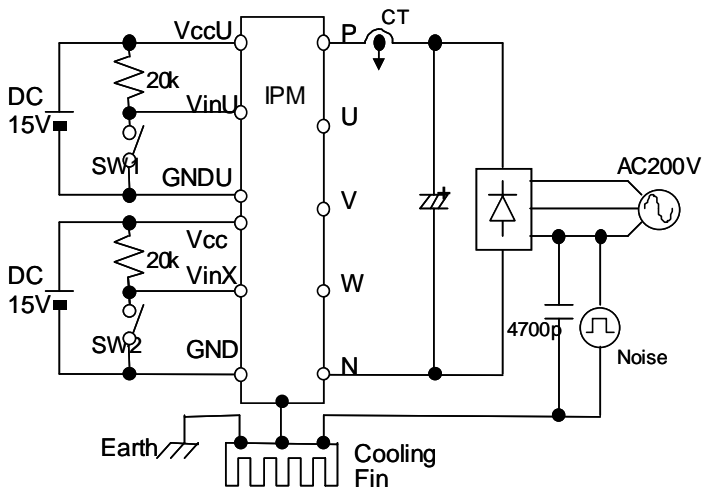


Figure 5. Noise Test Circuit

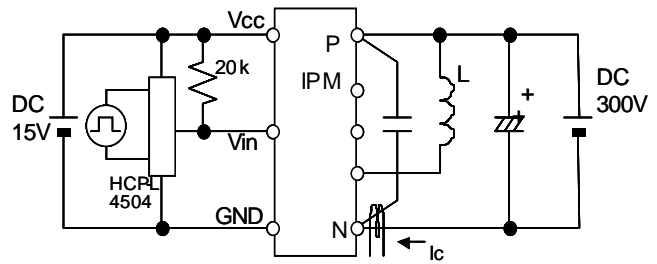


Figure 6. Switching Characteristics Test Circuit

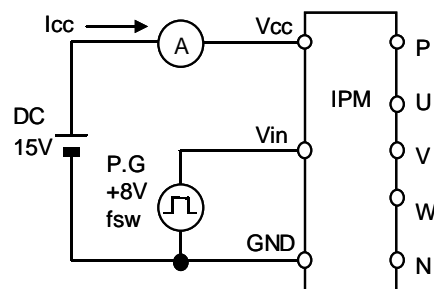
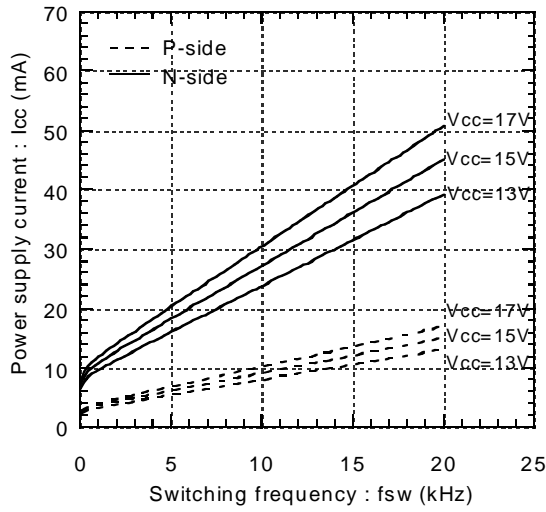


Figure 7. Icc Test Circuit

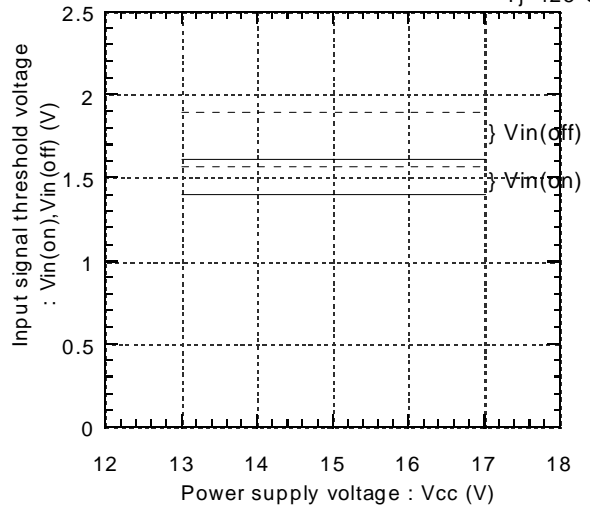
■ Characteristics

● Control circuit characteristics (Representative)

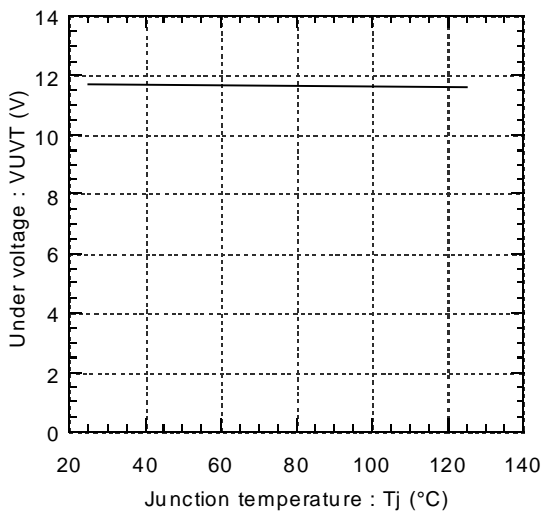
Power supply current vs. Switching frequency
Tc=125°C



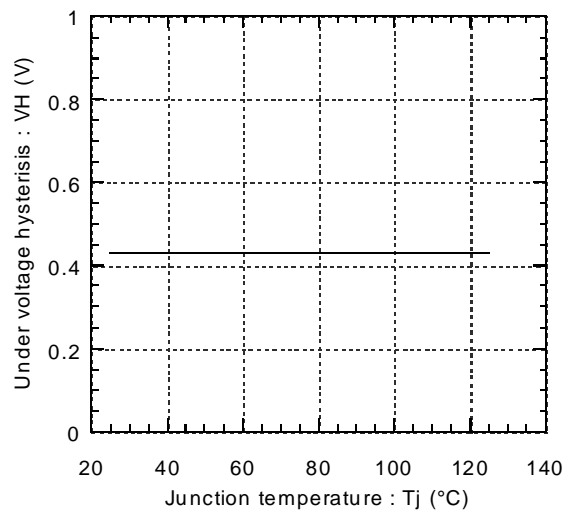
Input signal threshold voltage vs. Power supply voltage
— Tj=25°C
--- Tj=125°C



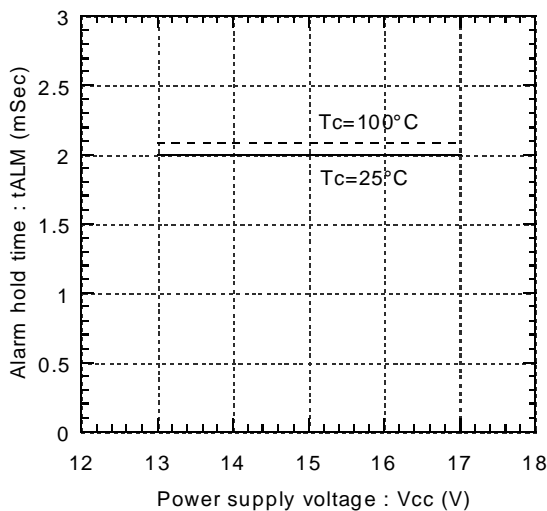
Under voltage vs. Junction temperature



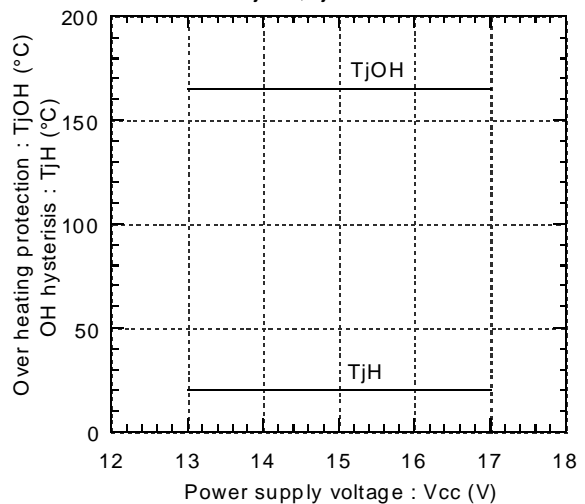
Under voltage hysteresis vs. Junction temperature



Alarm hold time vs. Power supply voltage

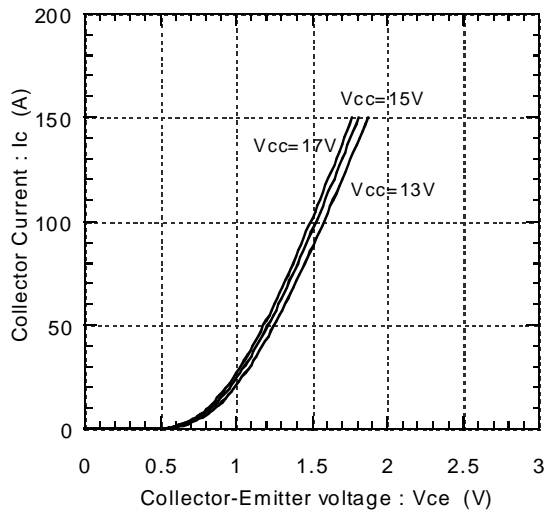


Over heating characteristics
TjOH, TjH vs. Vcc

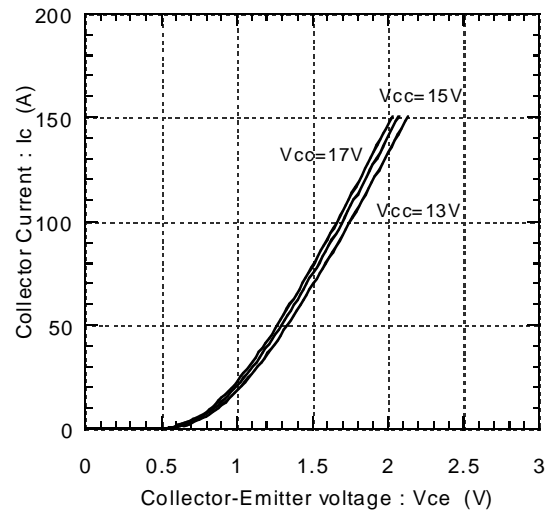


● Main circuit characteristics (Representative)

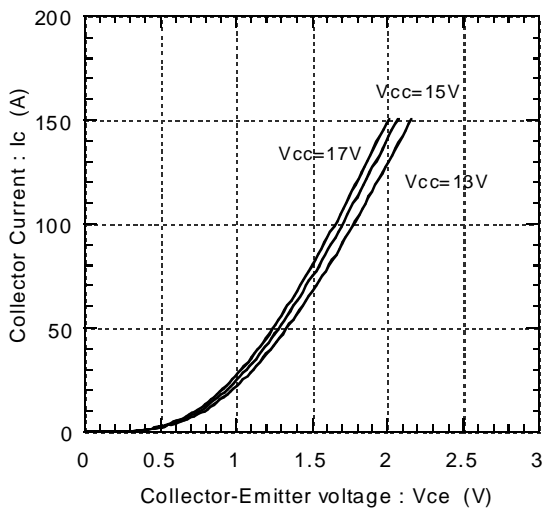
Collector current vs. Collector-Emitter voltage
T_j=25°C(Chip)



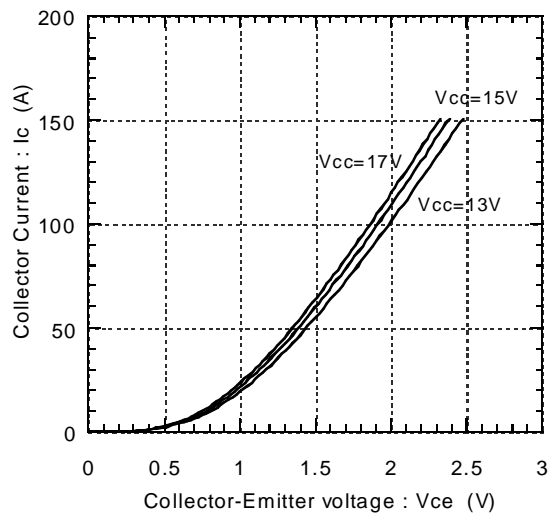
Collector current vs. Collector-Emitter voltage
T_j=25°C(Terminal)



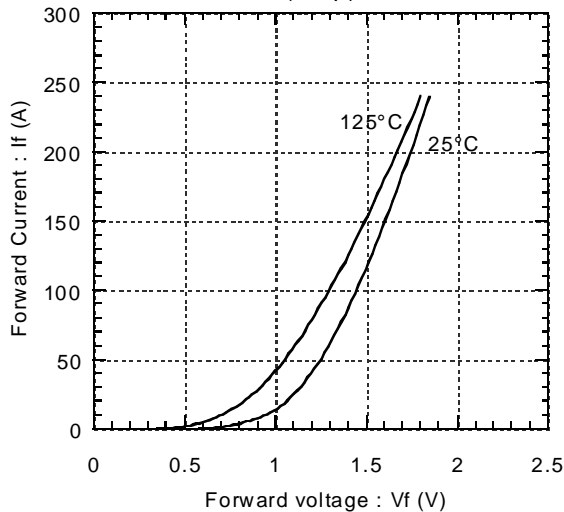
Collector current vs. Collector-Emitter voltage
T_j=125°C(Chip)



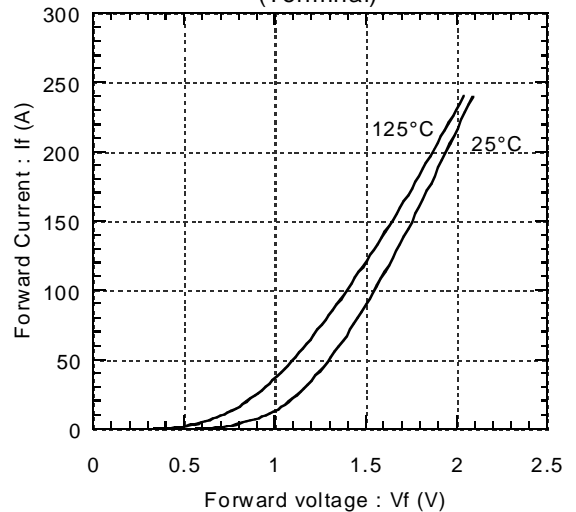
Collector current vs. Collector-Emitter voltage
T_j=125°C(Terminal)



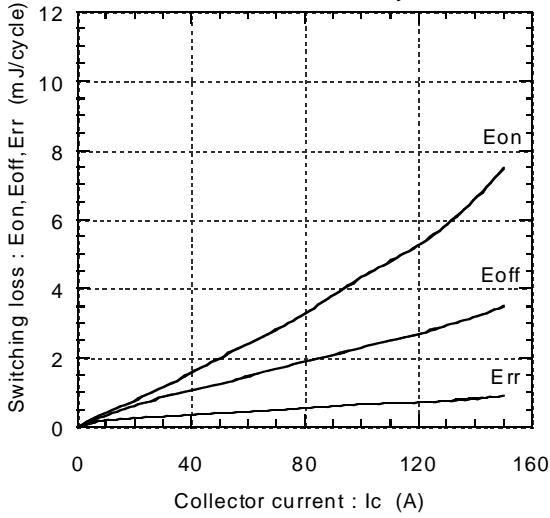
Forward current vs. Forward voltage
(Chip)



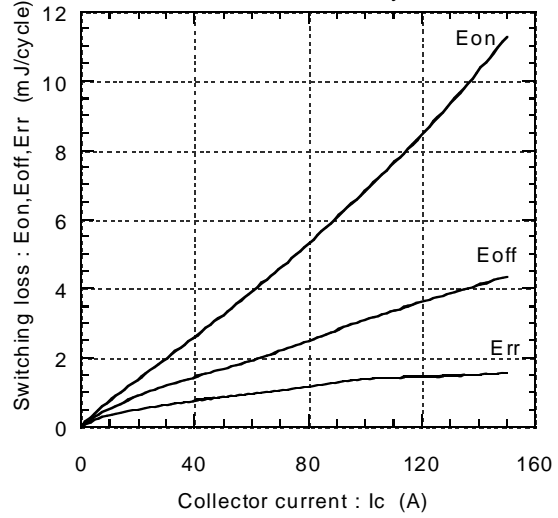
Forward current vs. Forward voltage
(Terminal)



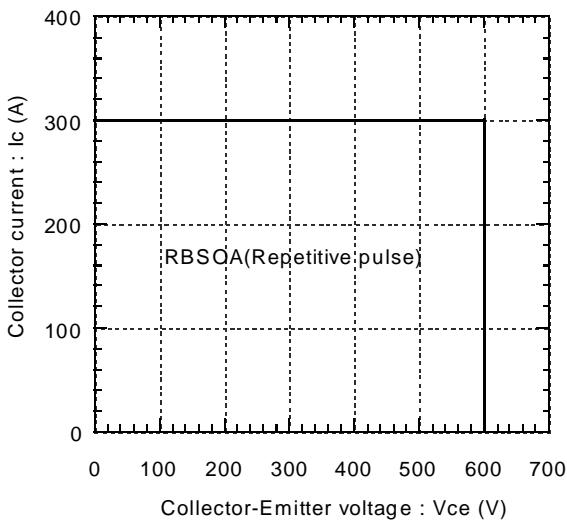
Switching Loss vs. Collector Current
 $E_{dc}=300V, V_{cc}=15V, T_j=25^\circ C$



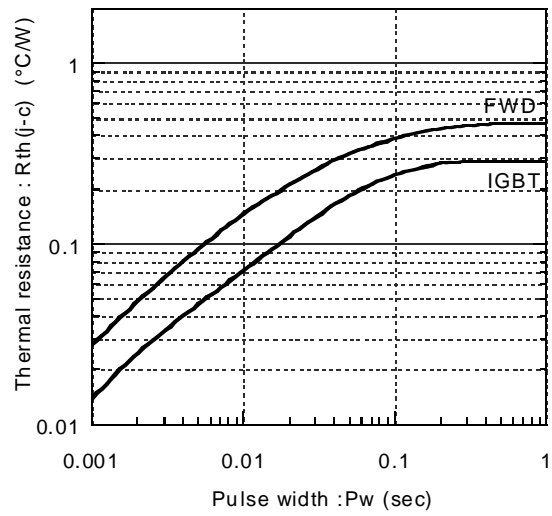
Switching Loss vs. Collector Current
 $E_{dc}=300V, V_{cc}=15V, T_j=125^\circ C$



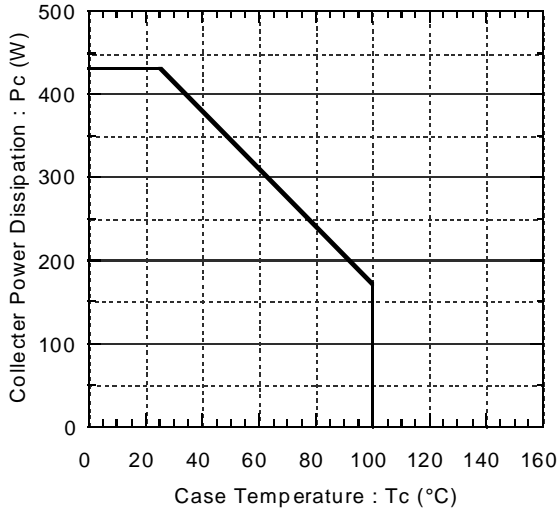
Reversed biased safe operating area
 $V_{cc}=15V, T_j 125^\circ C$



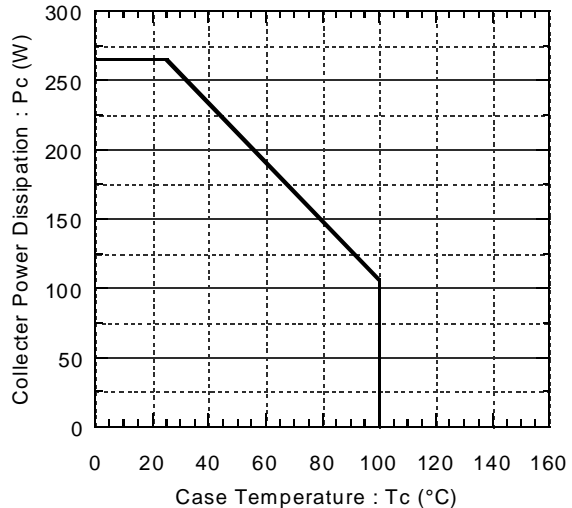
Transient thermal resistance



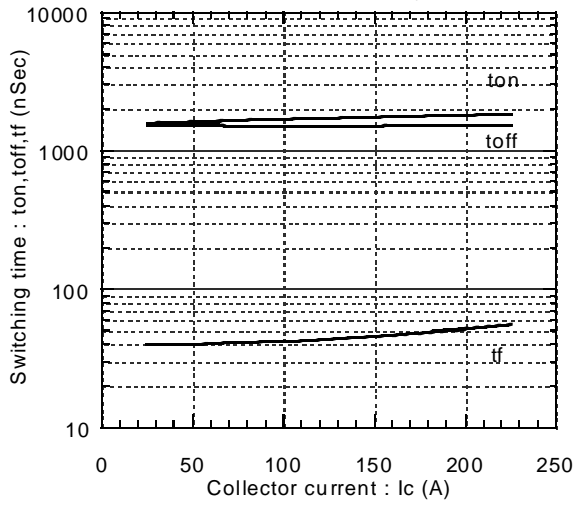
Power derating for IGBT
 (per device)



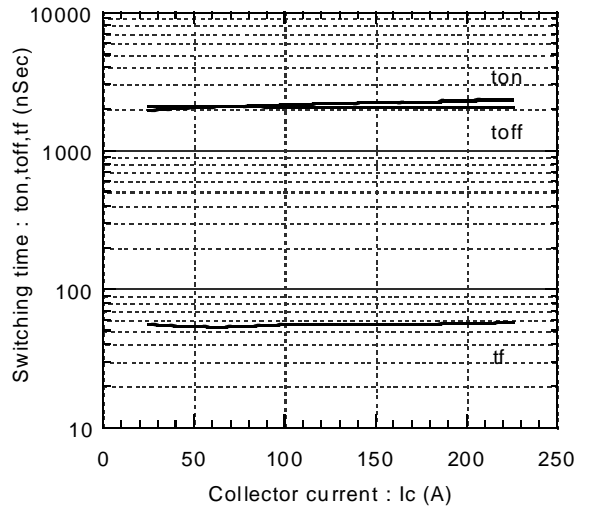
Power derating for FWD
 (per device)



Switching time vs. Collector current
 $E_{dc}=300V, V_{cc}=15V, T_j=25^\circ C$



Switching time vs. Collector current
 $E_{dc}=300V, V_{cc}=15V, T_j=125^\circ C$



Reverse recovery characteristics
 t_{rr}, I_{rr} vs. I_F

